

**Amendments to the Specification:**

Please replace the paragraph beginning on page 3, line 24 with the following amended paragraph:

A first embodiment of the invention is described with reference to Figure 1, which shows a computer cooling system 100. The system 100 includes an enclosure 102 sized and shaped to receive a typical computer tower case 122 in a main chamber thereof 104. The enclosure 102 is substantially airtight and has a front wall 103, top wall 101, and back wall 107. The enclosure further includes a panel or door 152 positioned to provide access to the disk drive bays 154 commonly found on the front side of the case 122. The panel 152 may be coupled to the enclosure 102 via hinges, clips, friction latches, magnetic catches, or other appropriate devices. The enclosure 102 includes an aperture 146 disposed in the rear of the enclosure 102. The aperture 146 is positioned and configured to provide passage for power and connection cables 150 from the interior of the enclosure 102 to peripheral devices such as video monitor 151 and keyboard 153, for example.

Please replace the paragraph beginning on page 6, line 22 with the following amended paragraph:

According to another embodiment, as illustrated in Figure 3, Jump cables 164 and jump ports 166 are provided in the back region 123 of the enclosure 102. The jump cables are configured, at first ends thereof, each to engage a service port 62 of the computer, 122. Typical service ports include USB ports, serial and parallel ports, keyboard and video monitor ports, etc. Each of the jump cables is configured to engage one side of a jump port 166, located on an inner surface of the enclosure 102. The jump ports extend through the wall of the enclosure 102 and provide a receptacle 167 on the outside of the enclosure, configured to receive a connector corresponding to the respective service port 162. In this manner, the integrity of the enclosure 102 is improved, and connection to the computer is made more convenient.

Please replace the paragraph beginning on page 9, line 3 with the following amended paragraph:

According to another embodiment of the invention, as illustrated in Figure 4, a second thermostat 142 is provided, together with the air exchange mechanism 156. When air

temperature within the back region 123 of the enclosure 102, as indicated by the thermostat 130, rises above the temperature of the air outside the enclosure 102, as indicated by thermostat 142, the air exchange mechanism 156 is activated by a control circuit 143 (shown diagrammatically), which causes air from the back region 123 to vent to the outside of the enclosure 102, while cooler air from the outside is drawn into the return duct 112 to be cooled, such that the coolest air available is drawn in, thus maximizing the economy of the system. Filter 132 serves to remove dust from the air, that would otherwise tend to foul the evaporator coils 116 and the components within the computer case 122.

Please replace the paragraph beginning on page 10, line 21 with the following amended paragraph:

According to the embodiment illustrated in Figure 7, a system 190 includes a cooling unit 105 incorporated into a computer case 200 itself. The system includes a chassis 198, to which may be coupled standard and optional components, including, for example, a power supply 194, a mother board, hard drive 195, and disk drives 197. The case includes a return duct 192 with an intake vent 199 located in an upper region of the case. A cover 202 is provided, configured to provide a substantially air tight seal when closed on to the case ~~200~~chassis 198.

Please replace the paragraph beginning on page 11, line 16 with the following amended paragraph:

An embodiment of the invention may provide a back-up system 129 (shown diagrammatically in Figure 1) configured to respond to a failure of the cooling unit. Such a back-up system may include combinations of ventilation panels, louvers, or fans configured to activate in the event of a loss of power, or function to the cooling unit, or in response to excessive temperature within the enclosure.